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SLLS641 – JANUARY 2005

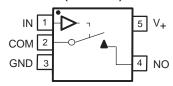
#### **Description**

The MAX4596 is a single-pole single-throw (SPST) analog switch that is designed to operate from 2 V to 5 V. This device can handle both digital and analog signals, and signals up to  $V_{+}$  (peak) can be transmitted in either direction.

#### **Applications**

- Sample-and-Hold Circuits
- Battery-Powered Equipment
- Audio and Video Signal Routing
- Communication Circuits

#### SOT-23 OR SC-70 PACKAGE (TOP VIEW)



#### **FUNCTION TABLE**

IN	NO TO COM, COM TO NO
L	OFF
Н	ON

#### **Features**

- Low ON-State Resistance (10 Ω)
- ON-State Resistance Flatness (1.5 Ω)
- Control Inputs Are 5.5-V Tolerant
- Low Charge Injection (5 pC Max)
- 300-MHz –3-dB Bandwidth at 25°C
- Low Total Harmonic Distortion (THD) (0.05%)
- 2-V to 5.5-V Single-Supply Operation
- Specified at 5-V and 3.3-V Nodes
- -83-dB OFF Isolation at 1 MHz
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- 0.5-nA Max OFF Leakage
- ESD Performance Tested Per JESD 22
  - 2000-V Human-Body Model (A114-B, Class II)
  - 1000-V Charged-Device Model (C101)
- TTL/CMOS-Logic Compatible

#### Summary of Characteristics

 $V_{+} = 5 \text{ V}, T_{A} = 25^{\circ}\text{C}$ 

Configuration	Single Pole Single Throw (SPST)
Number of channels	1
ON-state resistance (ron)	10 Ω
ON-state resistance flatness (ron(flat))	1.5 Ω
Turn-on/turn-off time (tON/tOFF)	35 ns/40 ns
Charge injection (Q <sub>C</sub> )	5 pC
Bandwidth (BW)	300 MHz
OFF isolation (O <sub>ISO</sub> )	-83 dB at 1 MHz
Total harmonic distortion (THD)	0.05%
Leakageourrent(ICOM(OFF)/INO(OFF))	±0.05 nA
Power-supply current (I+)	1 μΑ
Package option	5-pin SOT-23 or SC-70

#### ORDERING INFORMATION

TA	PACKAGE(1)		ORDERABLE PART NUMBER	TOP-SIDE MARKING(2)
4000 1- 0500	SOT (SOT-23) – DBV	Tape and reel	MAX4596DBVR	6SB_
-40°C to 85°C	SOT (SC-70) - DCK	Tape and reel	MAX4596DCKR	SB_

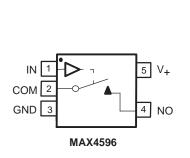
(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package. (2) DBV/DCK: The actual top-side marking has one additional character that designates the assembly/test site.

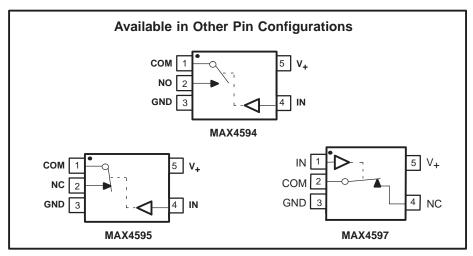


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#### **Pin Configurations**





## Absolute Minimum and Maximum Ratings(1)(2)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V <sub>+</sub>	Supply voltage range(3)	-0.3	6	V	
V <sub>NO</sub> V <sub>COM</sub>	Analog voltage range(3)(4)		-0.3	V <sub>+</sub> + 0.3	V
ΙK	Analog port diode current	V <sub>NO</sub> , V <sub>COM</sub> < 0	-50		mA
I <sub>NO</sub> I <sub>COM</sub>	On-state switch current	$V_{NO}$ , $V_{COM} = 0$ to $V_{+}$	-20	20	mA
I <sub>NO</sub> I <sub>COM</sub>	On-state switch current (pulsed at 1 ms, 10% duty cycle)	$V_{NO}$ , $V_{COM} = 0$ to $V_{+}$	-40	40	mA
VI	Digital input voltage range(3)(4)		-0.3	6	V
ΙΚ	Digital input clamp current	V <sub>I</sub> < 0	-50		mA
l <sub>+</sub>	Continuous current through V+			100	mA
IGND	Continuous current through GND		-100		mA
	Declined the arreal impact on a (5)	DBV package		206	0000
θJΑ	Package thermal impedance(5)	ackage thermal impedance(3)  DCK package		252	°CW
T <sub>stg</sub>	Storage temperature range		-65	150	°C

<sup>(1)</sup> Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied.

<sup>(2)</sup> The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum

<sup>(3)</sup> All voltages are with respect to ground, unless otherwise specified.

<sup>(4)</sup> The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

<sup>(5)</sup> The package thermal impedance is calculated in accordance with JESD 51-7.



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## Electrical Characteristics for 5-V Supply<sup>(1)</sup> $V_+ = 4.5 \text{ V}$ to 5.5 V, $T_A = -40 ^{\circ}\text{C}$ to $85 ^{\circ}\text{C}$ (unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITION	TA	٧+	MIN	TYP	MAX	UNIT						
Analog Switch														
Analog signal range	V <sub>COM</sub> , V <sub>NO</sub>					0		٧+	٧					
ON-state resistance	r <sub>on</sub>	V <sub>NO</sub> = 3.5 V I <sub>COM</sub> = 10 mA,	Switch ON, See Figure 13	25°C Full	4.5 V		6.5	10 12	Ω					
ON-state resistance	r(0-0)	V <sub>NO</sub> = 1.5 V, 2.5 V, 3.5 V	Switch ON,	25°C	4.5 V		0.5	1.5	Ω					
flatness	ron(flat)	$I_{COM} = 10 \text{ mA},$	See Figure 13	Full	4.5 V			2	22					
NO OFF leakage	luo(OFF)	V <sub>NO</sub> = 1 V, V <sub>COM</sub> = 4.5 V,	Switch OFF,	25°C	5.5 V	-0.5	0.01	0.5	nA					
current	INO(OFF)	V <sub>NO</sub> = 4.5 V, V <sub>COM</sub> = 1 V,	See Figure 14	Full	5.5 V	-5		5	IIA					
COM OFF leakage		$V_{COM} = 1 \text{ V}, V_{NO} = 4.5 \text{ V},$	Switch OFF,	25°C	5.5 V	-0.5	0.01	0.5	nA					
current	ICOM(OFF)	$V_{COM} = 4.5 \text{ V}, V_{NO} = 1 \text{ V},$	See Figure 14	Full		-5		5	II/A					
NO ON locks as		V <sub>NO</sub> = 1 V, V <sub>COM</sub> = 1 V,	Switch ON,	25°C	551	-1	0.01	1	- 4					
ON leakage current	INO(ON)	$V_{NO} = 4.5 \text{ V}, V_{COM} = 4.5 \text{ V},$ or $V_{NO} = 1 \text{ V}, 4.5 \text{ V}, V_{COM} = \text{Open},$	See Figure 15	Full	5.5 V	-10		10	nA					
COM		V <sub>COM</sub> = 1 V, V <sub>NO</sub> = 1 V,	Switch ON,	25°C	55.4	-1	0.01	1						
current	N leakage urrent		See Figure 15	Full	5.5 V	-10		10	nA					
Digital Control In	put (IN)													
Input logic high	VIH			Full		2.4		5.5	V					
Input logic low	V <sub>IL</sub>			Full		0		8.0	V					
Input leakage current	I <sub>IH</sub> , I <sub>IL</sub>	V <sub>I</sub> = V <sub>+</sub> or 0		25°C Full	5.5 V	-1 -1	0.03	1	μΑ					

<sup>(1)</sup> The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum

### **MAX4596** SINGLE-CHANNEL 10- $\Omega$ SPST ANALOG SWITCH



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# Electrical Characteristics for 5-V Supply<sup>(1)</sup> (continued) $V_+ = 4.5 \text{ V to } 5.5 \text{ V}, T_A = -40 ^{\circ}\text{C to } 85 ^{\circ}\text{C}$ (unless otherwise noted)

PARAMETER	SYMBOL	TEST COND	DITIONS	TA	٧+	MIN	TYP	MAX	UNIT
Dynamic									
Turn-on time	4	V <sub>NO</sub> = 3 V,	C <sub>L</sub> = 35 pF,	25°C	5 V		20	35	20
rum-on time	tON	$R_L = 300 \Omega$ ,	See Figure 17	Full	4.5 V to 5.5 V			45	ns
Turn-off time	tOFF	$V_{COM} = 3 V$	$C_L = 35 pF$ ,	25°C	5 V		25	40	ns
Tarri on time	OFF	$R_L = 300 \Omega$ ,	See Figure 17	Full	4.5 V to 5.5 V			50	113
Charge injection	QC	V <sub>GEN</sub> = 0, R <sub>GEN</sub> = 0, C <sub>L</sub> = 1 nF,	See Figure 20	25°C	5 V		2	5	pC
NO OFF capacitance	C <sub>NO(OFF)</sub>	$V_{NO} = V_{+}$ or GND, f = 1 MHz,	Switch OFF, See Figure 16	25°C	5 V		8		pF
COM OFF capacitance	CCOM(OFF)	V <sub>COM</sub> = V <sub>+</sub> or GND, f = 1 MHz,	Switch OFF, See Figure 16	25°C	5 V		8		pF
NO ON capacitance	C <sub>NO(ON))</sub>	V <sub>NO</sub> = V <sub>+</sub> or GND, f = 1 MHz,	Switch ON, See Figure 16	25°C	5 V		20		pF
COM ON capacitance	C <sub>COM(ON)</sub>	V <sub>COM</sub> = V <sub>+</sub> or GND, f = 1 MHz,	Switch ON, See Figure 16	25°C	5 V		20		pF
Digital input capacitance	Cl	$V_I = V_+$ or GND,	See Figure 16	25°C	5 V		3		pF
Bandwidth	BW	$R_L = 50 \Omega$ , Signal = 0 dBm,	Switch ON, See Figure 18	25°C	5 V		300		MHz
OFF isolation	O <sub>ISO</sub>	$R_L = 50 \Omega$ , $C_L = 5 pF$ , $V_{NO} = 1 V_{RMS}$ , $f = 1 MHz$ ,	Switch OFF, See Figure 19	25°C	5 V		-83		dB
Total harmonic distortion	THD	$R_L = 600 \Omega$ , $C_L = 50 pF$ , $V_{SOURCE} = 5 V_{p-p}$ ,	f = 20 Hz to 20 kHz, See Figure 21	25°C	5 V		0.05	·	%
Supply	•	•			•	•			
Positive supply current	l <sub>+</sub>	$V_I = V_+$ or GND,	Switch ON or OFF	Full	5.5 V			1	μА

<sup>(1)</sup> The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum



### **MAX4596** SINGLE-CHANNEL 10- $\Omega$ SPST ANALOG SWITCH

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## Electrical Characteristics for 3-V Supply<sup>(1)</sup> $V_+ = 2.7 \text{ V to } 3.6 \text{ V}, T_A = -40 ^{\circ}\text{C} \text{ to } 85 ^{\circ}\text{C} \text{ (unless otherwise noted)}$

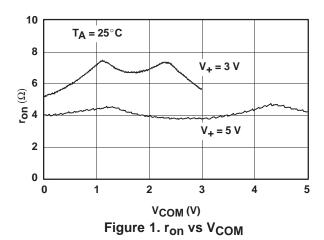
PARAMETER	SYMBOL	TEST CON	TA	٧+	MIN	TYP	MAX	UNIT	
Analog Switch									
Analog signal range	V <sub>COM</sub> , V <sub>NO</sub>					0		٧+	٧
ON-state	r	V <sub>NO</sub> = 1.5 V,	Switch ON,	25°C	2.7 V		10	20	Ω
resistance	ron	$I_{COM} = 10 \text{ mA},$	See Figure 13	Full	2.7 V			25	22
Digital Control Inp	out (IN)								
Input logic high	VIH			Full		2		5.5	V
Input logic low	VIL			Full		0		0.8	V
Input leakage		V V == 0		25°C	0.01/	-1	0.03	1	
current	¹IH, ¹IL	$V_I = V_+ \text{ or } 0$		Full	3.6 V	-1		1	μΑ
Dynamic									
Turn-on time		V <sub>NO</sub> = 2 V,	C <sub>L</sub> = 35 pF,	25°C	3 V		25	45	
rum-on time	tON	$R_L = 300 \Omega$ ,	See Figure 17	Full	2.7 V to 3.6 V			55	ns
Turn-off time		V <sub>NO</sub> = 2 V,	C <sub>L</sub> = 35 pF,	25°C	3 V		30	50	
Turn-off time	tOFF	$R_L = 300 \Omega$ ,	See Figure 17	Full	2.7 V to 3.6 V			60	ns
Charge injection	QC	V <sub>GEN</sub> = 0, R <sub>GEN</sub> = 0, C <sub>L</sub> = 1 nF,	See Figure 20	25°C	3 V		2	4	рС
Supply									
Positive supply current	l <sub>+</sub>	$V_I = V_+$ or GND,	Switch ON or OFF	Full	3.6 V			1	μΑ

<sup>(1)</sup> The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum



#### TYPICAL PERFORMANCE

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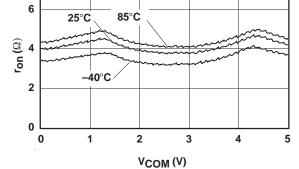
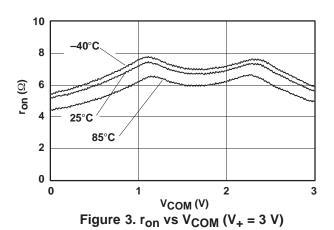
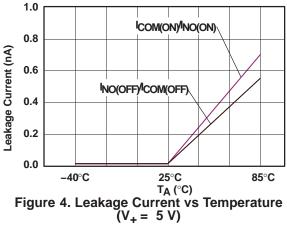
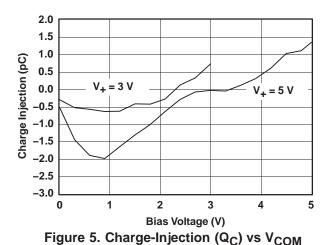


Figure 2.  $r_{on}$  vs  $V_{COM}$  ( $V_{+} = 5 V$ )







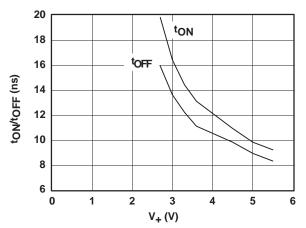


Figure 6. toN and toFF vs Supply Voltage



#### TYPICAL PERFORMANCE

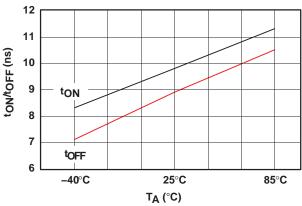


Figure 7.  $t_{ON}$  and  $t_{OFF}$  vs Temperature (V<sub>+</sub> = 5 V)

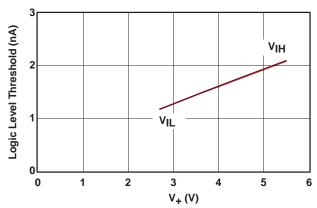


Figure 8. Logic-Level Threshold vs V<sub>+</sub>

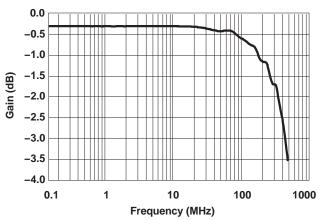


Figure 9. Bandwidth (Gain vs Frequency)  $(V_+ = 5 \text{ V})$ 

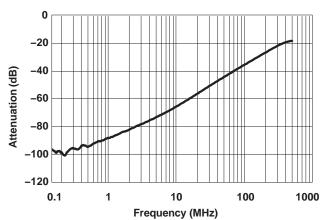


Figure 10. Off Isolation vs Frequency

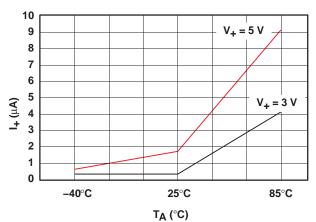


Figure 11. Power-Supply Current vs Temperature

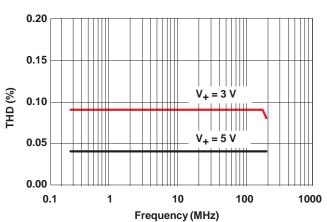


Figure 12. Total Harmonic Distortion vs Frequency

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#### **PIN DESCRIPTION**

PIN NUMBER	NAME	DESCRIPTION
1	IN	Digital control pin to connect COM to NO
2	COM	Common
3	GND	Digital ground
4	NO	Normally open
5	V <sub>+</sub>	Power supply

#### PARAMETER DESCRIPTION

SYMBOL	DESCRIPTION
VCOM	Voltage at COM
V <sub>NO</sub>	Voltage at NO
r <sub>on</sub>	Resistance between COM and NO ports when the channel is ON
ron(flat)	Difference between the maximum and minimum value of ron in a channel over the specified range of conditions
I <sub>NO</sub> (OFF)	Leakage current measured at the NO port, with the corresponding channel (NO to COM) in the OFF state
I <sub>NO(ON)</sub>	Leakage current measured at the NO port, with the corresponding channel (NO to COM) in the ON state and the output (COM) open
ICOM(OFF)	Leakage current measured at the COM port, with the corresponding channel (COM to NO) in the OFF state
ICOM(ON)	Leakage current measured at the COM port, with the corresponding channel (COM to NO) in the ON state and the output (NO) open
VIH	Minimum input voltage for logic high for the control input (IN)
VIL	Maximum input voltage for logic low for the control input (IN)
VI	Voltage at the control input (IN)
I <sub>IH</sub> , I <sub>IL</sub>	Leakage current measured at the control input (IN)
ton	Turn-on time for the switch. This parameter is measured under the specified range of conditions and by the propagation delay between the digital control (IN) signal and analog output (COM or NO) signal when the switch is turning ON.
tOFF	Turn-off time for the switch. This parameter is measured under the specified range of conditions and by the propagation delay between the digital control (IN) signal and analog output (COM or NO) signal when the switch is turning OFF.
QC	Charge injection is a measurement of unwanted signal coupling from the control (IN) input to the analog (NO or COM) output. This is measured in coulomb (C) and measured by the total charge induced due to switching of the control input. Charge injection, $Q_C = C_L \times \Delta V_{COM}$ , $C_L$ is the load capacitance, and $\Delta V_{COM}$ is the change in analog output voltage.
C <sub>NO(OFF)</sub>	Capacitance at the NO port when the corresponding channel (NO to COM) is OFF
C <sub>NO(ON)</sub>	Capacitance at the NO port when the corresponding channel (NO to COM) is ON
CCOM(OFF)	Capacitance at the COM port when the corresponding channel (COM to NO) is OFF
C <sub>COM(ON)</sub>	Capacitance at the COM port when the corresponding channel (COM to NO) is ON
Cl	Capacitance of control input (IN)
O <sub>ISO</sub>	OFF isolation of the switch is a measurement of OFF-state switch impedance. This is measured in dB in a specific frequency, with the corresponding channel (NO to COM) in the OFF state.
BW	Bandwidth of the switch. This is the frequency in which the gain of an ON channel is -3 dB below the DC gain.
THD	Total harmonic distortion describes the signal distortion caused by the analog switch. This is defined as the ratio of root mean square (RMS) value of the second, third, and higher harmonic to the absolute magnitude of the fundamental harmonic.
l <sub>+</sub>	Static power-supply current with the control (IN) pin at V <sub>+</sub> or GND



#### PARAMETER MEASUREMENT INFORMATION

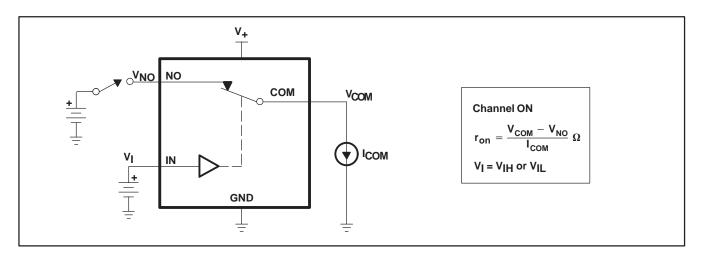


Figure 13. ON-State Resistance (ron)

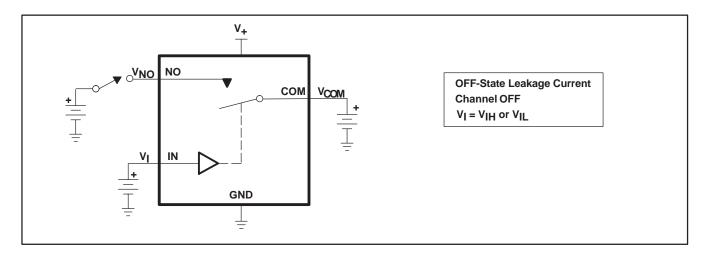


Figure 14. OFF-State Leakage Current ( $I_{COM(OFF)}$ ,  $I_{NO(OFF)}$ )

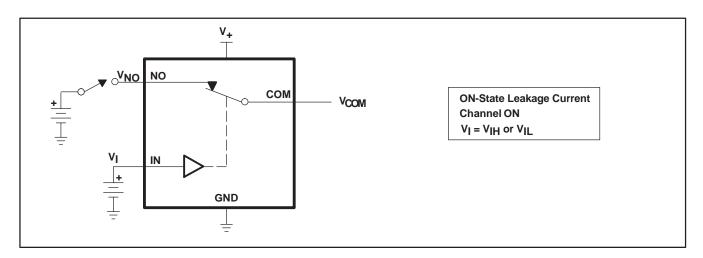


Figure 15. ON-State Leakage Current ( $I_{COM(ON)}$ ,  $I_{NO(ON)}$ )



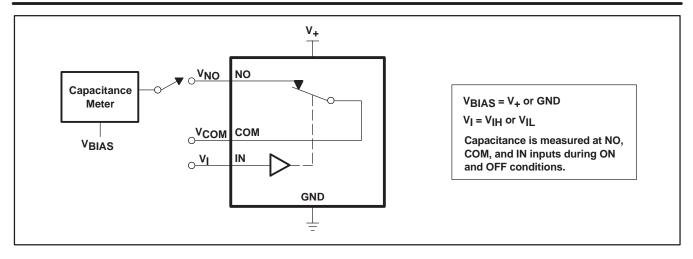
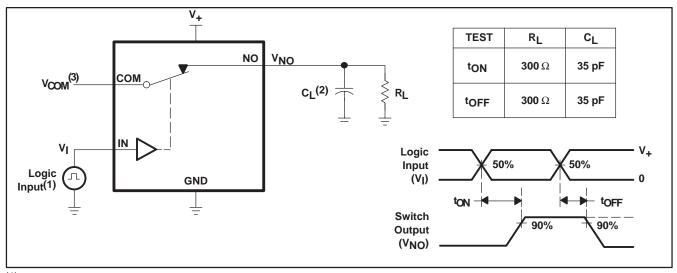


Figure 16. Capacitance (C<sub>I</sub>, C<sub>COM(OFF)</sub>, C<sub>COM(ON)</sub>, C<sub>NO(OFF)</sub>, C<sub>NO(ON)</sub>)



- (1) All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz, Z<sub>O</sub> = 50  $\Omega$ , t<sub>f</sub> < 5 ns. t<sub>f</sub> < 5 ns.
- (2) C<sub>L</sub> includes probe and jig capacitance.
- (3) See Electrical Characteristics for V<sub>COM</sub>.

Figure 17. Turn-On (t<sub>ON</sub>) and Turn-Off Time (t<sub>OFF</sub>)

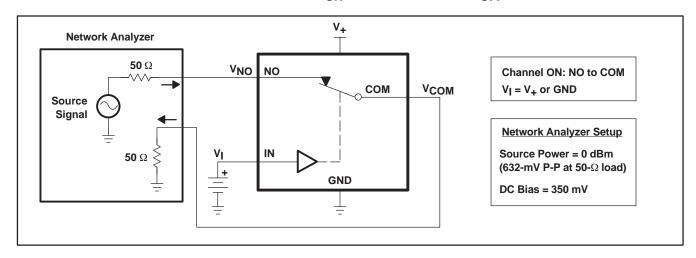


Figure 18. Bandwidth (BW)



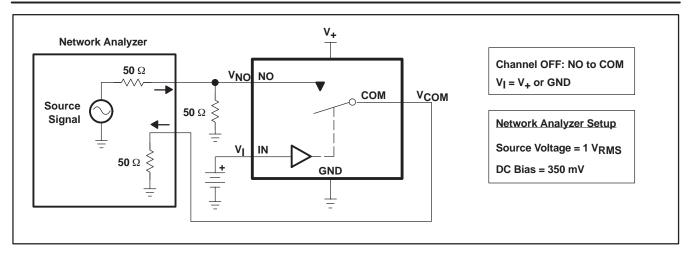
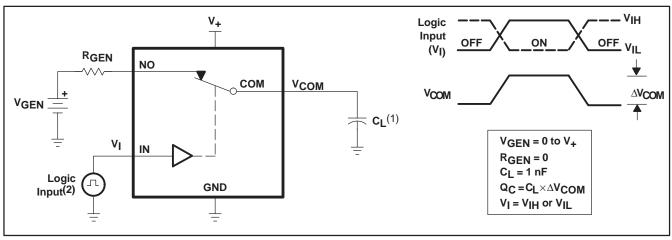
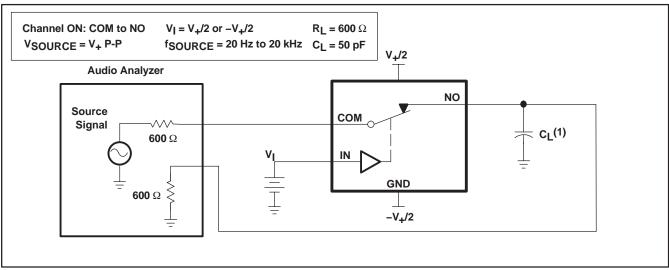


Figure 19. OFF Isolation (OISO)



- (1) C<sub>L</sub> includes probe and jig capacitance.
- (2) All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \Omega$ ,  $t_f < 5 \text{ ns}$ ,  $t_f < 5 \text{ ns}$ .

Figure 20. Charge Injection (Q<sub>C</sub>)



(1) C<sub>I</sub> includes probe and jig capacitance.

Figure 21. Total Harmonic Distortion (THD)

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#### PACKAGING INFORMATION

Orderable part number	Status	Material type	Package   Pins	Package qty   Carrier	RoHS	Lead finish/	MSL rating/	Op temp (°C)	Part marking
	(1)	(2)			(3)	Ball material	Peak reflow		(6)
						(4)	(5)		
MAX4596DBVR	Active	Production	SOT-23 (DBV)   5	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	6SCR
MAX4596DBVR.B	Active	Production	SOT-23 (DBV)   5	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	6SCR
MAX4596DCKR	Active	Production	SC70 (DCK)   5	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	SCR
MAX4596DCKR.B	Active	Production	SC70 (DCK)   5	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	SCR
MAX4596DCKRG4	Active	Production	SC70 (DCK)   5	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	SCR
MAX4596DCKRG4.B	Active	Production	SC70 (DCK)   5	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	SCR

<sup>(1)</sup> Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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<sup>(2)</sup> Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

<sup>(4)</sup> Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.



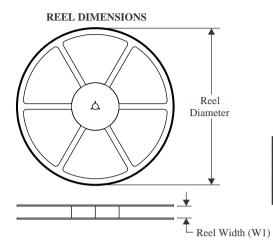
## **PACKAGE OPTION ADDENDUM**

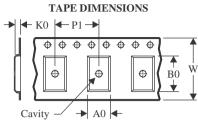
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## **PACKAGE MATERIALS INFORMATION**

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#### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
MAX4596DBVR	SOT-23	DBV	5	3000	180.0	8.4	3.23	3.17	1.37	4.0	8.0	Q3
MAX4596DCKR	SC70	DCK	5	3000	180.0	8.4	2.47	2.3	1.25	4.0	8.0	Q3
MAX4596DCKRG4	SC70	DCK	5	3000	180.0	8.4	2.47	2.3	1.25	4.0	8.0	Q3

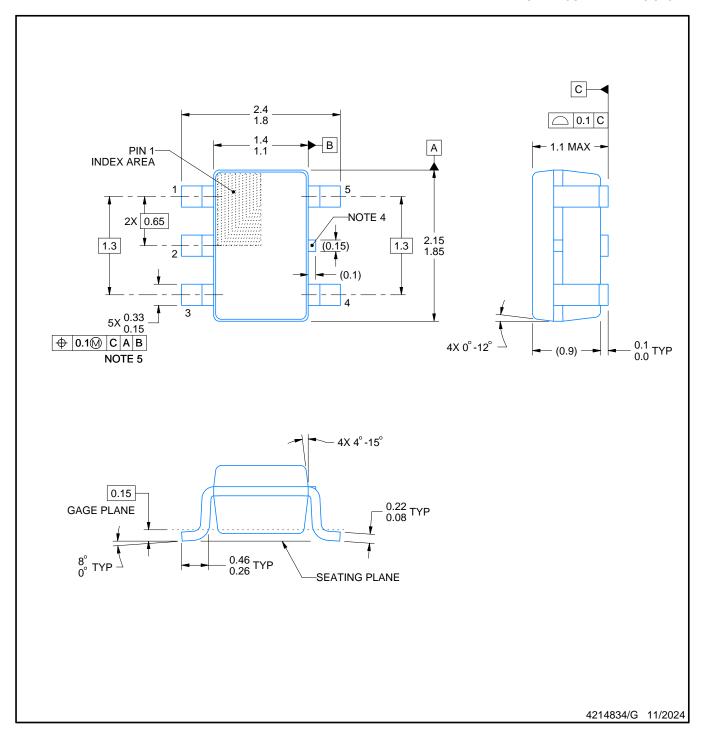
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#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
MAX4596DBVR	SOT-23	DBV	5	3000	202.0	201.0	28.0
MAX4596DCKR	SC70	DCK	5	3000	202.0	201.0	28.0
MAX4596DCKRG4	SC70	DCK	5	3000	202.0	201.0	28.0



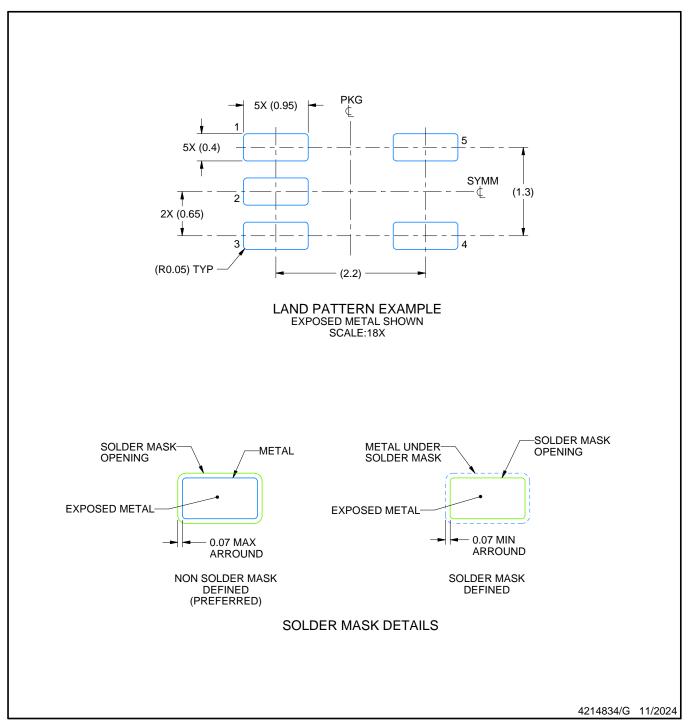


#### NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
  2. This drawing is subject to change without notice.
  3. Reference JEDEC MO-203.

- 4. Support pin may differ or may not be present.5. Lead width does not comply with JEDEC.
- 6. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25mm per side

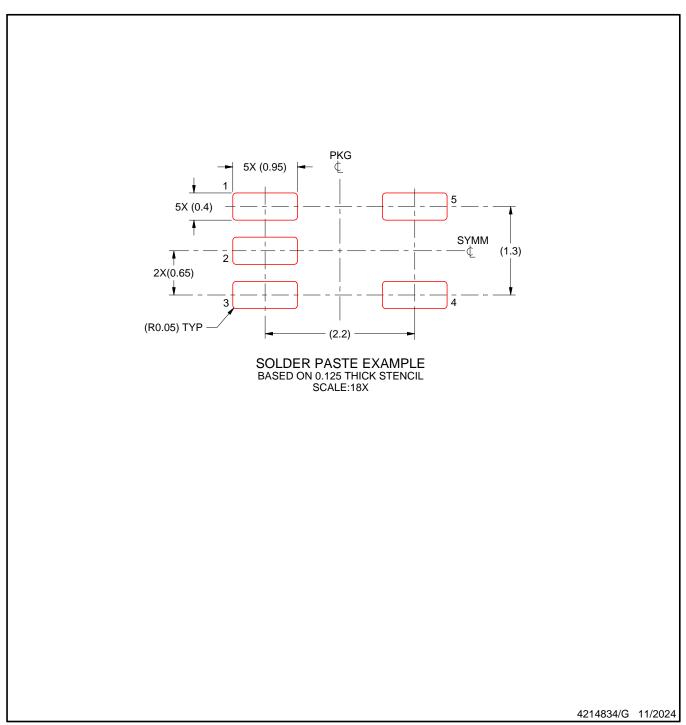




NOTES: (continued)

7. Publication IPC-7351 may have alternate designs.8. Solder mask tolerances between and around signal pads can vary based on board fabrication site.





NOTES: (continued)

- 9. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 10. Board assembly site may have different recommendations for stencil design.







#### NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
  2. This drawing is subject to change without notice.
  3. Reference JEDEC MO-178.

- 4. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25 mm per side.
- 5. Support pin may differ or may not be present.





NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.





NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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